



PRODUCT DESCRIPTION

Tgrease™ 300X is a silicone-based thermal grease for use with high performance CPUs, GPUs, custom ASICs, Multi-Chip, SoC, etc. It has a high thermal conductivity of 3.0 W/mK and superior wetting characteristics, resulting in very low thermal resistance and excellent long-term reliability. Tgrease™ 300X has been formulated with a high thixotropic index. It does not sag or drip enabling easier pump and syringe dispensing. Tgrease™ 300X is ideal for automatic dispensing and screen-printing.

FEATURES & BENEFITS

- 3.0 W/mK bulk thermal conductivity
- Low thermal resistance
- Resists pump out through novel gel technology
- Fully characterized long term reliability
- Unique formulas will not harden, dry out, settle, or oxidize.
- Environmentally friendly solution that meets regulatory requirements including RoHS and REACH

MARKETS

- Semiconductor Packaging
- Graphics Card
- Notebooks
- Desktops
- Servers
- IGBTs
- Automotive
- Memory Modules

AVAILABILITY

- Available in 1kg (quart container), cartridges and custom syringes

STORAGE CONDITIONS

- Store 15°C to 45°C & maximum 50% RH
- Shelf Life unopened: 2 year from date of mix when stored at above conditions

TYPICAL PROPERTIES

PROPERTY	VALUE	TEST METHOD
Construction	Silicone Thermal Grease	N/A
Color	Grey	Visual
Density	2.7 g/cc	Helium Pycnometer
Bulk Thermal Conductivity	3.0 W/m-K	Hot Disk
Thermal Resistance		
10 psi & 50°C	0.20°C-cm ² /W	ASTM D5470
50 psi & 50°C	0.12°C-cm ² /W	
Operating Temperature Range	-40°C to 150°C	Laird Test Method
Viscosity	400,000 cP	Brookfield Viscometer - TF spindle at 20rpm (helipath) at 23°C
Thixotropic Index	3.35	Brookfield Viscometer
Minimum Bond Line Thickness	25 µm	Laird Test Method
Outgassing (TML)	0.07%	E595
Outgassing (CVCM)	0.01%	E595
Dielectric Constant	28.3@1KHz / 31.8@1MHz	ASTM D150
Dissipation Factor	0.014@1KHz / 0.005@1MHz	ASTM D150
Volume Resistivity	1.0x10 ¹⁴ Ω-cm	ASTM D991

USA: +1.866.928.8181
Europe: +49.8031.24600
Asia: +86.755.2714.1166
www.laird.com

